



# Product Change Notification

## 103928 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 103928 - 00  
**Change Title:** Intel® TXN174012013F06 10GBASE-LR XENPAK, PCN 103928-00, FYI, Assembly Site Change to Malaysia.  
**Date of Publication:** February 26, 2004

## Type of Change Notification:

FYI - (For Your Information)

## Key Characteristics of the Change:

Manufacturing Site  
Product Marking

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	May 15, 2004
<b>Date of First Availability of Post-Conversion Material:</b>	Feb 26, 2004

*The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.*

## Description of Change to the Customer:

Intel® TXN174012013F06 10GBASE-LR XENPAK optical transceiver will be assembled at a 2nd factory in Malaysia starting March 2004. Customers can distinguish these units by referring to the product serial numbers and country of origin: current product made in the USA has serial numbers starting with "USC" and country of origin showing "Made in USA", whereas product assembled from our 2nd factory will have serial numbers starting with "MY" and with words "Made in Malaysia".

Assembly and Test processes are the same as the US factory. Starting in March 2004, USA factory will perform post testing and quality inspect all Intel® TXN174012013F06 products manufactured at the 2nd factory before shipping to customers. After May 15 2004 the 2nd factory will be handling all assembly, test and customer shipments. The optical module inside the transceiver (transmitter and receiver) will continue to be manufactured at the OPD Newark California site in the USA with no intention for transition.

Customers should expect some product assembled from the 2nd factory in Malaysia and post tested by the USA factory starting in March 2004.

### **Customer Impact of Change and Recommended Action:**

No customer action is required. Product manufactured from the 2nd factory is the same as current product being shipped with the exception of serial number and country of origin marking.

### **Products Affected / Intel Ordering Codes:**

#### **System Products Table**

<b>Affected Product Code</b>	<b>MM#</b>
TXN174012013F06	855749
TXN174012013F06	856221
TXN174012013F06	856223
TXN174012013F06	856224
TXN174012013F06	856409

### **Reference Documents / Attachments:**

**Document:**

**Location #:**

### **PCN Revision History:**

**Date of Revision:**

**Revision Number:**

**Reason:**

February 26, 2004

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Originally Published PCN